



Product Change Notification: MFOL-02TSEI860

Date:

13-Jul-2026

Product Category:

Memory

Notification Subject:

CCB 8135 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material and QMI519 as a new die attach material for 24FC04, 24LC02BH, 24LC04B, 24FC02, 24LC02B, 24AA01, 24AA02, 24LC01B, 24LC04BH, 24FC04H, 24AA04, 24LC01BH, 24FC01, 24AA04H, 24AA01H, 24AA02H, AT24C08C, AT24C16D, 24AA16H, 24LC16BH, 24FC08, 24LC08B, AT24C16C, 24AA08H, 24AA08, 24AA16, 24LC08BH, 24FC16H, 24FC16, and 24LC16B device families available in 8L SOIC (3.90mm) package at MMT assembly site.

Affected CPNs:

[MFOL-02TSEI860_Affected_CPN_07132026.pdf](#)

[MFOL-02TSEI860_Affected_CPN_07132026.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material and QMI519 as a new die attach material for 24FC04, 24LC02BH, 24LC04B, 24FC02, 24LC02B, 24AA01, 24AA02, 24LC01B, 24LC04BH, 24FC04H, 24AA04, 24LC01BH, 24FC01, 24AA04H, 24AA01H, 24AA02H, AT24C08C, AT24C16D, 24AA16H, 24LC16BH, 24FC08, 24LC08B, AT24C16C, 24AA08H, 24AA08, 24AA16, 24LC08BH, 24FC16H, 24FC16, and 24LC16B device families available in 8L SOIC (3.90mm) package at MMT assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change (Yes/No)

Assembly Site	Microchip Technology Thailand (Branch) (MMT)	Microchip Technology Thailand (Branch) (MMT)	No
Wire Material	Au	CuPdAu	Yes
Die Attach Material	8390A (PFAS-Free)	QMI519 (PFAS-Free)	Yes
Molding Compound Material	G600V	G600V	No
Lead-Frame Material	CDA194	CDA194	No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) as a new bond wire material and QMI519 as a new die attach material.

Change Implementation Status: In Progress

Estimated First Ship Date: 03 June 2026 (date code: 2623)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	March 2026					>	June 2026				
Work Week	10	11	12	13	14		23	24	25	26	27
Qual Report Availability		X									
Final PCN Issue Date		X									
Estimated Implementation Date							X				

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: March 12, 2026: Issued final notification.

July 13, 2026: Re-issued final notification to remove the note referencing PCN CENO-16EGCZ399 for the QMI519 Qualification Report from the Pre and Post summary changes. Attached an additional Qualification Report for the Die Attach Material instead.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_MFOL-02TSEI860_Qual Report.pdf

PCN_MFOL-02TSEI860_Qual Report For Die Attach Material.pdf

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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If you wish to [change your PCN profile, including opt out,](#) please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN):

24AA16-I/SN
24AA08-I/SN
24LC08BH-I/SN
24AA08T/SN
24FC16H-I/SN
24AA16T-E/SN
24FC08T-E/SN
24FC16HT-E/SN
24LC16BHT-E/SN
24FC16T-E/SN
24LC16BT-E/SN
24LC08BT-E/SN
24FC16-I/SN
24AA16-E/SN
24LC08BH-E/SN
24FC08-E/SN
24FC16H-E/SN
24LC16BH-E/SN
24FC16-E/SN
24LC16B-E/SN
24LC16B/SN
24AA08/SN
24LC16B-I/SN
24LC08BHT-E/SN
24LC16BT-I/SN
24FC04H-I/SN
24FC04-I/SN
24FC02-I/SN
24LC02B-I/SN
24LC01BH-I/SN
24FC01-I/SN
24LC04B-E/SN

MFOL-02TSEI860 - CCB 8135 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material and QMI519 as a new die attach material for 24FC04, 24LC02BH, 24LC04B, 24FC02, 24LC02B, 24AA01, 24AA02, 24LC01B, 24LC04BH, 24FC04H, 24AA04, 24LC01BH, 24FC01, 24AA04H, 24AA01H, 24AA02H, AT24C08C, AT24C16D, 24AA16H, 24LC16BH, 24FC08, 24LC08B,

24LC01BT-I/SN

24AA04T/SN

24AA01T/SN

24LC04BT/SN

24LC02BT/SN

24LC01BT/SN

24AA04-I/SN

24FC01-E/SN

24FC04-E/SN

24FC02-E/SN

AT24C08C-SSHM-T

AT24C08C-SSHM-B

AT24C16C-SSHM-T

AT24C16D-SSHM-B

24AA16H-I/SN

24LC16BH-I/SN

24FC08-I/SN

24LC08B-I/SN

AT24C16D-SSHM-T

24AA16T-I/SN

24LC08BHT-I/SN

24LC08B-E/SN

24LC08B/SN

24FC04T-E/SN

24LC02BHT-E/SN

24LC04BT-E/SN

24FC02T-E/SN

24LC02BT-E/SN

24AA01/SN

24AA02/SN

24LC04B/SN

24LC01B/SN

24LC02B/SN

24LC04BHT-E/SN

24FC04HT-E/SN

24AA04/SN

24AA08HT-I/SN

24AA08T-I/SN

24AA16HT-I/SN

24LC01B-I/SN

24LC02BH-E/SN

24LC01BT-E/SN

24FC01T-E/SN

24AA04HT-I/SN

24AA04T-I/SN

24AA02T-I/SN

24AA02HT-I/SN

24AA01T-I/SN

24FC04HT-I/SN

24FC04T-I/SN

24LC04BHT-I/SN

24LC04BT-I/SN

24FC01T-I/SN

24AA02H-I/SN

24LC01BHT-E/SN

24AA01HT-I/SN

24LC02BT-I/SN

24LC01BHT-I/SN

24AA02-I/SN

24LC01BH-E/SN

24LC02BHT-I/SN

24FC02T-I/SN

24LC04BH-E/SN

24LC02B-E/SN

24AA02T/SN

24AA04H-I/SN

24AA01H-I/SN

24AA01-I/SN

24LC04BH-I/SN

24LC02BH-I/SN

24LC04B-I/SN

MFOL-02TSEI860 - CCB 8135 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material and QMI519 as a new die attach material for 24FC04, 24LC02BH, 24LC04B, 24FC02, 24LC02B, 24AA01, 24AA02, 24LC01B, 24LC04BH, 24FC04H, 24AA04, 24LC01BH, 24FC01, 24AA04H, 24AA01H, 24AA02H, AT24C08C, AT24C16D, 24AA16H, 24LC16BH, 24FC08, 24LC08B, 24LC01B-E/SN

24FC04H-E/SN

24FC08T-I/SN

24LC08BT-I/SN

24FC16HT-I/SN

24LC16BHT-I/SN

24FC16T-I/SN

24LC08BT/SN

24LC16BT/SN

AT24C16C-SSHM-B

24AA08H-I/SN



Qualification Report Summary

RELIABILITY LABORATORY

PCN #: MFOL-02TSEI860

Date: May 4, 2026

Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material and QMI519 as a new die attach material for 24FC04, 24LC02BH, 24LC04B, 24FC02, 24LC02B, 24AA01, 24AA02, 24LC01B, 24LC04BH, 24FC04H, 24AA04, 24LC01BH, 24FC01, 24AA04H, 24AA01H, 24AA02H, AT24C08C, AT24C16D, 24AA16H, 24LC16BH, 24FC08, 24LC08B, AT24C16C, 24AA08H, 24AA08, 24AA16, 24LC08BH, 24FC16H, 24FC16, and 24LC16B device families available in 8L SOIC (3.90mm) package at MMT assembly site will qualify by similarity.

PACKAGE QUALIFICATION REPORT

Purpose:

Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material and QMI519 as a new die attach material for 24FC04, 24LC02BH, 24LC04B, 24FC02, 24LC02B, 24AA01, 24AA02, 24LC01B, 24LC04BH, 24FC04H, 24AA04, 24LC01BH, 24FC01, 24AA04H, 24AA01H, 24AA02H, AT24C08C, AT24C16D, 24AA16H, 24LC16BH, 24FC08, 24LC08B, AT24C16C, 24AA08H, 24AA08, 24AA16, 24LC08BH, 24FC16H, 24FC16, and 24LC16B device families available in 8L SOIC (3.90mm) package at MMT assembly site will qualify by similarity.

QUAL ID:	R2600333 Rev. A
MP CODE:	VNAA17C2XA00
Part No.:	RE46C100S8F
Bonding No.:	BD-004161 rev 01
CCB No.:	8077

Lead Frame

Paddle Size:	90x90 mils
Material:	A194
DAP Surface Prep:	Selective Ag Plating
Treatment:	BOT
Process:	Etched
Lead Lock:	Yes
Part Number:	10100857
Lead Plating:	Matte Tin
Strip Size:	239.6x70mm
Strip Density:	320 pads/strip

Bond Wire

Wire:	CuPdAu wire
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Die Attach Material

Epoxy:	QMI519
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Mold Compound

Mold Compound:	G600V
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Package

Type:	8L SOIC
Package Size:	150 mils

PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.
MMT-264800051.000
MMT-264801191.000
MMT-264801255.000

Result: PASS

Conclusion:

Qualification of VNAA1 mask / RE46C100S8F product / CuPdAu wire in 8L SOIC 150 mils (C2X) package at MTAI site is qualified for MSL1 at 260°C as per JEDEC J-STD-020 standard and is passed in accordance to Specified JEDEC and Mil Standards

PACKAGE QUALIFICATION REPORT

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result
Moisture Soak Precondition Prior to Stresses	MSL1: 150°C 24 hours Bake, 168 hours Moisture Soak at 85°C/85%RH, 3x Reflow at 260°C Electrical Test: 25°C and 85°C Tester: ETS300	JESD22-A113, JEDEC J-STD-020	231 units each lot / 3 lots	Electrical Results: 0/231 (R26 00333-1 M MT-264800 051.000), 0/231 (R26 00333-2 M MT-264801 191.000), 0/231 (R26 00333-3 M MT-264801 255.000);	Pass

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result
High Temp Storage	175°C / 504 hours Electrical Test: 25°C and 85°C Tester: ETS300	JESD22-A103	45 units / 3 lot	Electrical Results: 0/45 (R260 0333-1 MM T-2648000 51.000), 0/45 (R260 0333-2 MM T-2648011 91.000), 0/45 (R260 0333-3 MM T-2648012 55.000)	Pass

Tes	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result
Temperature Cycling	-65°C / +150°C Air to Air / 500 Cycles Electrical Test: 25°C and 85°C Tester: ETS300	JESD22-A104	77 units each lot / 3 lots	Electrical Results: 0/77 (R260 0333-1 MM T-2648000 51.000), 0/77 (R260 0333-2 MM T-2648011 91.000), 0/77 (R260 0333-3 MM T-2648012 55.000); WBP: 0/5 (R2600333-1), N/A (R2600333-2), N/A (R2600333-3);	Pass

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result
Biased HAST	+130°C / 85%RH / 96 hours / Bias Voltage: 16.0V Electrical Test: 25°C and 85°C Tester: ETS300	JESD22-A110	77 units each lot / 3 lots	Electrical Results: 0/77 (R260 0333-1 MM T-2648000 51.000), 0/77 (R260 0333-2 MM T-2648011 91.000), 0/77 (R260 0333-3 MM T-2648012 55.000);	Pass

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result
Unbiased HAST	+130°C / 85%RH / 96 hours Electrical Test: 25°C and 85°C Tester: ETS300	JESD22-A118	77 units each lot / 3 lots	Electrical Results: 0/77 (R260 0333-1 MM T-2648000 51.000), 0/77 (R260 0333-2 MM T-2648011 91.000), 0/77 (R260 0333-3 MM T-2648012 55.000);	Pass

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result
Solderability (0 Hr) Method 1: Dip and Look	Pb-free 8 hours Steam age. Dip at 245°C, 100% leads >95% lead coverage	J-STD-002 / JESD22B-102	22 units / 1 lot	Visual Result: 0/22	Pass

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result
Physical Dimension (0Hr)	Within package diagram dimension	JESD22 B100 and B108	10 units each lot / 3 lots	0/30	Pass

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result
Wire Pull	Bond Strength Data Assembly	Mil. Std. 883-2011	5 units / 1 lot	0/5	Pass

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result
Bond Shear	Bond Strength Data Assembly	CDF-AEC-Q100 -001	5 units / 1 lot	0/5	Pass



MICROCHIP
QUALIFICATION REPORT SUMMARY
RELIABILITY LABORATORY

PCN #: MFOL-02TSEI860

Date:
October 30, 2017

Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material and QMI519 as a new die attach material for 24FC04, 24LC02BH, 24LC04B, 24FC02, 24LC02B, 24AA01, 24AA02, 24LC01B, 24LC04BH, 24FC04H, 24AA04, 24LC01BH, 24FC01, 24AA04H, 24AA01H, 24AA02H, AT24C08C, AT24C16D, 24AA16H, 24LC16BH, 24FC08, 24LC08B, AT24C16C, 24AA08H, 24AA08, 24AA16, 24LC08BH, 24FC16H, 24FC16, and 24LC16B device families available in 8L SOIC (3.90mm) package at MMT assembly site will qualify by similarity.



MICROCHIP

PACKAGE QUALIFICATION REPORT

Purpose	Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material and QMI519 as a new die attach material for 24FC04, 24LC02BH, 24LC04B, 24FC02, 24LC02B, 24AA01, 24AA02, 24LC01B, 24LC04BH, 24FC04H, 24AA04, 24LC01BH, 24FC01, 24AA04H, 24AA01H, 24AA02H, AT24C08C, AT24C16D, 24AA16H, 24LC16BH, 24FC08, 24LC08B, AT24C16C, 24AA08H, 24AA08, 24AA16, 24LC08BH, 24FC16H, 24FC16, and 24LC16B device families available in 8L SOIC (3.90mm) package at MMT assembly site will qualify by similarity.
CN	ES122649
QUAL ID	Q17142
MP CODE	VDEB1YC2XA00
Part No.	HV9801ALG-G
Bonding No.	BDM-001461 Rev. A
CCB No.	3047 and 8135
<u>Package</u>	
Type	8L SOIC
Package size	150 mils
<u>Lead Frame</u>	
Paddle size	90 x 90 mils
Material	CDA194
Surface	Ag Spot Plated
Process	Stamped
Lead Lock	No
Part Number	10100824
Treatment	Roughened
<u>Material</u>	
Epoxy	84-1LMISR4
Wire	Au wire
Mold Compound	G600V
Plating Composition	Matte Tin



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PACKAGE QUALIFICATION REPORT

Manufacturing Information:

Assembly Lot No.	Wafer Lot No.	Date Code
MMT-181900976.000	TC 02915142031.300	1731QQ1
MMT-181901189.000	TC 02915142031.300	1731VAE
MMT-182000221.000	TC 02915142031.300	1732VAG

Result ☒ Pass ☐ Fail ☐ _____

8L SOIC (.150") assembled by MMT (ALPH) pass reliability test per QCI-39000. This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020D standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
Moisture/Reflow Sensitivity Classification Test (At MSL Level 1)	85°C/ 85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243 (IPC/JEDEC J-STD-020D)	IPC/JEDEC C J-STD- 020D	135	0/135	Pass	

<u>Precondition Prior Perform Reliability Tests (At MSL Level 1)</u>	Electrical Test :+25°C and 125°C System: TMT_HV_NT	JESD22- A113	693(0)	693		Good Devices
	Bake 150°C, 24 hrs System: CHINEE			693		
	85°C/85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH			693		
	3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243			693		
	Electrical Test :+25°C and 125°C System: TMT_HV_NT			0/693	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
TEMP CYCLE	Stress Condition: -65°C to +150°C, 500 Cycles System : TABAI ESPEC TSA-70H Electrical Test: + 125°C System: TMT_HV_NT Bond Strength: Wire Pull (> 2.5 grams) Bond Shear (>15.00 grams)	JESD22-A104		231		Parts had been pre-conditioned at 260°C
			231(0)	0/231	Pass	77 units / lot
			15 (0)	0/15	Pass	
			15 (0)	0/15	Pass	
UNBIASED-HAST	Stress Condition: +130°C/85%RH, 96 hrs. System: HAST 6000X Electrical Test: +25°C System: TMT_HV_NT	JESD22-A118		231		Parts had been pre-conditioned at 260°C
			231(0)	0/231	Pass	77 units / lot
HAST	Stress Condition: +130°C/85%RH, 96 hrs. Bias Volt: 30.0 Volts System: HAST 6000X Electrical Test: +25°C and 125°C System: TMT_HV_NT	JESD22-A110		231		Parts had been pre-conditioned at 260°C
			231(0)	0/231	Pass	77 units / lot
High Temperature Storage Life	Stress Condition: Bake 175°C, 504 hrs System: SHEL LAB Electrical Test: +25°C and 125°C System: TMT_HV_NT	JESD22-A103		45		45 units
			45(0)	0/45	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Bond Strength Data Assembly	Wire Pull (> 2.5 grams)	M2011	30 (0) Wires	0/30	Pass	
	Bond Shear (>15.00 grams)	JESD22- B116	30 (0) bonds	0/30	Pass	



QUALIFICATION REPORT SUMMARY
RELIABILITY LABORATORY

PCN #: MFOL-02TSEI860

Date:
May 5, 2017

Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material and QMI519 as a new die attach material for 24FC04, 24LC02BH, 24LC04B, 24FC02, 24LC02B, 24AA01, 24AA02, 24LC01B, 24LC04BH, 24FC04H, 24AA04, 24LC01BH, 24FC01, 24AA04H, 24AA01H, 24AA02H, AT24C08C, AT24C16D, 24AA16H, 24LC16BH, 24FC08, 24LC08B, AT24C16C, 24AA08H, 24AA08, 24AA16, 24LC08BH, 24FC16H, 24FC16, and 24LC16B device families available in 8L SOIC (3.90mm) package at MMT assembly site will qualify by similarity.



MICROCHIP

PACKAGE QUALIFICATION REPORT

Purpose	Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material and QMI519 as a new die attach material for 24FC04, 24LC02BH, 24LC04B, 24FC02, 24LC02B, 24AA01, 24AA02, 24LC01B, 24LC04BH, 24FC04H, 24AA04, 24LC01BH, 24FC01, 24AA04H, 24AA01H, 24AA02H, AT24C08C, AT24C16D, 24AA16H, 24LC16BH, 24FC08, 24LC08B, AT24C16C, 24AA08H, 24AA08, 24AA16, 24LC08BH, 24FC16H, 24FC16, and 24LC16B device families available in 8L SOIC (3.90mm) package at MMT assembly site will qualify by similarity.
CN	ES090904-18972
QUAL ID	QTP2900 Rev. A
MP CODE	355B27D3XC03
Part No.	ATTINY84-20SSU
Bonding No.	BDM-001250 rev B
CCB No.	2831 and 8135
<u>Package</u>	
Type	14L SOIC
Package size	150 mils
<u>Lead Frame</u>	
Paddle size	104x150 mils
Material	A194
Surface	Bare Cu
Process	Etched
Lead Lock	No
Part Number	10101413
Treatment	BOT
<u>Material</u>	
Epoxy	8390A
Wire	CuPdAu
Mold Compound	G600V
Plating Composition	Matte Tin



MICROCHIP PACKAGE QUALIFICATION REPORT

Manufacturing Information:

Assembly Lot No.	Wafer Lot No.	Date Code
MMT-174600763.000	MCSO517450071.000	1706KKA
MMT-174600764.000	MCSO 517 4500 71.000	1706KKB
MMT-174600765.000	MCSO517450071.000	1706KKC

Result ☒ Pass ☐ Fail ☐ _____

14L SOIC (.150") assembled by MMT (ALPH) pass reliability test per QCI-39000 which was conducted at MPHL rel lab. This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020D standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
<u>Precondition</u> <u>Prior Perform</u> <u>Reliability Tests</u> (At MSL Level 1)	Electrical Test :+85°C System: MT9320 Handler:0202 0hr CSAM Bake 150°C, 24 hrs System: HERAEUS 85°C/85%RH Moisture Soak 168 hrs. System: Climats Excal 5423-HE 3x Convection-Reflow 265°C max System: Mancorp CR.5000F Electrical Test :+85°C System: MT9320 Handler:0202	JESD22-A113 IPC/JEDEC J-STD-020D	846(0) 846	846 22 846 846 846	Pass	Good Devices
	Stress Condition: (Standard) 65°C to +150°C, 500 Cycles System : VOTSCH VT 7012 S2 Electrical Test: + 85°C System: MT9320 Handler:0202 Bond Strength: Wire Pull (> 2.50 grams) Bond Shear (>15.00 grams)	JESD22-A104	248(0)	0/248	Pass	Parts had been pre-conditioned at 260°C
	Stress Condition: (Extended) -65°C to +150°C, 1000 Cycles System : VOTSCH VT 7012 S2 Electrical Test: + 85°C System: MT9320 Handler:0202 Bond Strength: Wire Pull (>2.50 grams) Bond Shear (>15.00 grams)		15(0)	0/15	Pass	
			233(0)	0/233	Pass	
			18(0)	0/18	Pass	
Temp Cycle				240		

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
UNBIASED- HAST	Stress Condition: (Standard) +130°C/85%RH, 96 hrs. System: HIRAYAMA HASTEST PC-422R8	JESD22- A118		252		Parts had been pre-conditioned at 260°C
	Electrical Test: +85°C System: MT9320 Handler: 0202		252(0)	0/252	Pass	
	Stress Condition: (Extended) +130°C/85%RH, 192 hrs. System: HIRAYAMA HASTEST PC-422R8			251		
	Electrical Test: +85°C System: MT9320 Handler: 0202		251(0)	0/251	Pass	
HAST	Stress Condition: (Standard) +130°C/85%RH, 96 hrs. Bias Volt: 5.5 Volts System: HIRAYAMA HASTEST PC-422R8	JESD22- A110		240		Parts had been pre-conditioned at 260°C
	Electrical Test: +85°C System: MT9320 Handler:0202		240(0)	0/240	Pass	
	Stress Condition: (Extended) +130°C/85%RH, 192 hrs. Bias Volt: 5.5 Volts System: HIRAYAMA HASTEST PC-422R8			228		
	Electrical Test: +85°C System: MT9320 Handler:0202		228(0)	0/228	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
High Temperature Storage Life	Stress Condition: Bake 175°C, 504 hrs System: HERAEUS Electrical Test: +85°C System: MT9320 Handler:0202	JESD22-A103	45(0)	45 0/45	Pass	45 units
Solderability Temp 215°C	Steam Aging: Temp 93°C,8Hrs System: SAS-3000 Solder Dipping: Solder Temp.215°C Solder material: SnPb Sn63,Pb37 System: ERS RA 2200D Visual Inspection: External Visual Inspection	JESD22B-102E	22 (0)	22 22 0/22	Pass	Performed at MTAI
Solderability Temp 245°C	Steam Aging: Temp 93°C,8Hrs System: SAS-3000 Solder Dipping: Solder Temp.245°C Solder material: Pb Free Sn 95.5Ag3.9Cu0.6 System: ERS RA 2200D Visual Inspection: External Visual Inspection	JESD22B-102E	22 (0)	22 22 0/22	Pass	Performed at MTAI
Physical Dimensions	Physical Dimension, 30 units from 1 lot	JESD22-B100/B108	30(0) Units	0/30	Pass	
Bond Strength Data Assembly	Wire Pull (> 2.50 grams) Bond Shear (>15.00 grams)	M2011.8 MIL-STD-883	30 (0) Wires 30 (0) bonds	0/30 0/30		